



LED

xLED

xLED-VOS-8030 Pin Fin LED Heat Sink Φ 80mm for Vossloh-Schwabe

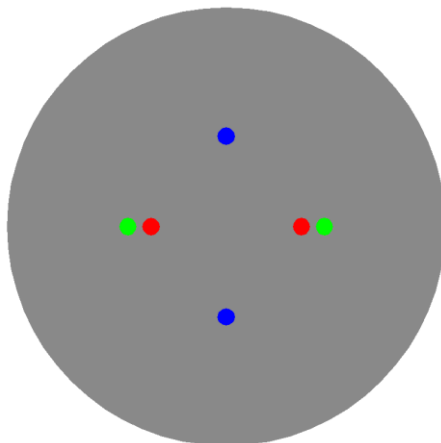
Features VS Benefits

- * The xLED-VOS-8030 Vossloh-Schwabe Pin Fin LED Heat Sinks are specifically designed for luminaires using the Vossloh-Schwabe LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,000 to 2,600 lumen.
- * Thermal resistance range Rth 3.13°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Vossloh-Schwabe COB series.
- * Diameter 80.0mm - standard height 30.0mm Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Vossloh-Schwabe COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



Vossloh-Schwabe LED Modules directly Mounting Options

Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (28.0*28.0):

- DMS120***G; DMS120***H;
- DMS12C***G; DMS12C***H;
- DMS18C***G; DMS18B***H;
- DMS18Q***G;

Vossloh-Schwabe LUGA Shop TW COB Series:

- TW2817;
- TW2820;
- With the Zhaga Book 3 holders for the green indicator marks.
- BJB holder: 47.319.2030.50;
- AAG STUCCHI: 8102-G2
- Without the holders for the blue indicator marks.
- Direct mounting with machine screws M3x6.5mm.

Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (19.0*19.0):

- DMS124***G; DMS125***H;
- DMS125***G; DMS126***H;
- DMS126***G; DMS128***H;
- DMS128***G;

Vossloh-Schwabe LUGA Shop TW COB Series:

- TW1914;
- With the Zhaga Book 3 holders for the green indicator marks.
- BJB holder: 47.319.2021.50;
- AAG STUCCHI: 8101-G2
- Without the holders for the red indicator marks.
- Direct mounting with machine screws M3x6.5mm.



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Mounting Options and Drawings & Dimensions

Example: xLED-VOS-8030-B-1,2

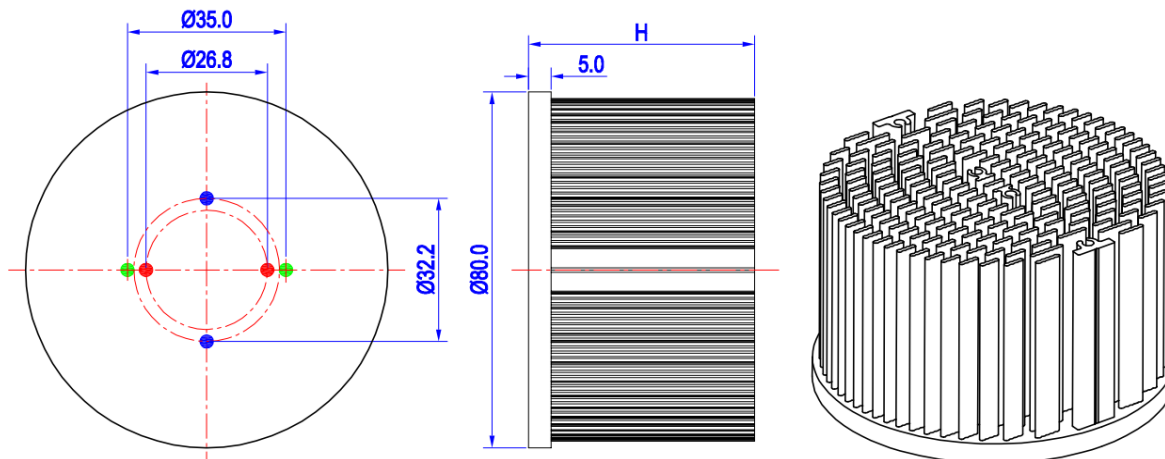
Example: xLED-VOS-80 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
 - B-Black
 - C-Clear
 - Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
 Ex.order code - 12
 means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	COB series (19.0*19.0)	/	M3	6.5mm	26.8mm/ 2-@180°
2		/	M3	6.5mm	32.2mm/ 2-@180°
3	COB series (28.0*28.0)	BJB Holder 47.319.2030.50	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8102-G2			
	COB series (19.0*19.0)	BJB Holder 47.319.2021.50			
		AAG.STUCCHI 8101-G2			



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The product data table

	Model No.	xLED-VOS-8030
	Heatsink Size	Φ 80xH30mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	140.0
	Dissipated power (Ths-amb,50°C)	16.0 (W)
	Cooling surface area (mm²)	72123
	Thermal Resistance (Rhs-amb)	3.13 (°C/W)

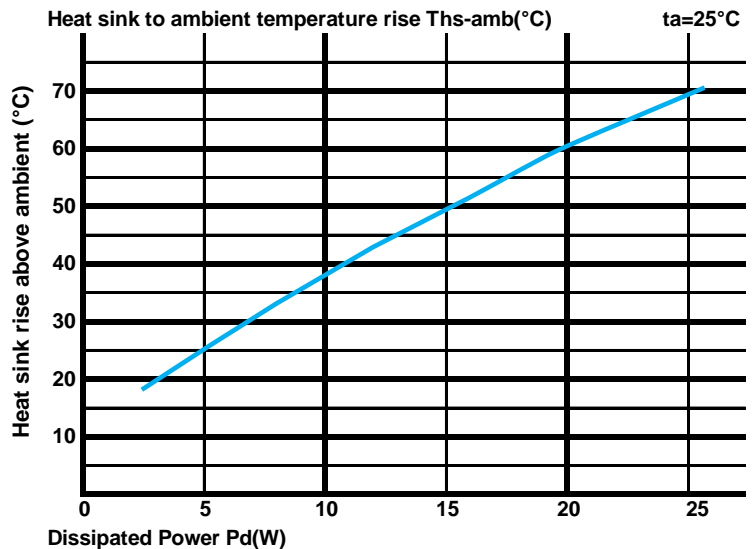
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

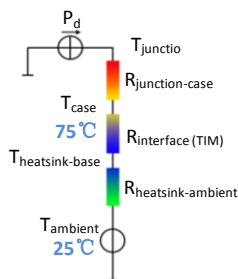
Dissipated Power Pd(W)	Heat sink to ambient thermal resistance Rhs-amb (°C/W)		Heat sink to ambient temperature rise Ths-amb (°C)	
	xLED-VOS-8030			
5.0	5.00	25.0		
10.0	3.80	38.0		
15.0	3.27	49.0		
20.0	3.00	60.0		
25.0	2.76	69.0		



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta) / Pd$

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$$